SHARP PC356NT/PC358

# PC356NT/PC358

#### **■** Features

1. High collector-emitter voltage

(PC358 ••• $V_{CEO}: 120V, PC356NT ••• V_{CEO}: 80V$ )

2. Opaque type, mini-flat package **PC356NT/PC358** (1-channel)

3. Subminiature type
(The volume is smaller than that of our conventional DIP type by as far as 30%)

4. Isolation voltage between input and output PC356NT/PC358 ••• V iso: 3 750 Vrms

5. Recognized by UL (No. E64380)

## ■ Applications

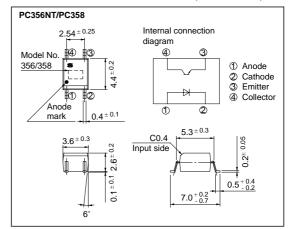
- 1. Hybrid substrates that require high density mounting
- 2. Programmable controllers

## ■ Package Specifications

Model No.	Package specifications				
PC356NT	Taping reel diameter 178mm ( 750pcs.)	_			
PC358	Taping reel diameter 370mm (3000pcs.)	_			

# Mini-Flat Package, High Collector-emitter Voltage Type Photocoupler

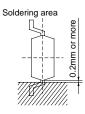
■ Outline Dimensions (Unit: mm)



## ■ Absolute Maximum Ratings

$(T_0 -$	25°	$\mathbf{C}$
(Ta =	23	C,

Parameter			Symbol	Rating	Unit
	Forward current		$I_{\mathrm{F}}$	50	mA
Input	*1Peak forward current		$I_{FM}$	1	A
	Reverse voltage		V <sub>R</sub>	6	V
	Power dissipation		P	70	mW
Output	Collector-emitter	PC356NT	17	80	V
	voltage	PC358	V CEO	120	V
	Emitter-collector voltage		V ECO	6	V
	Collector current		$I_{\rm C}$	50	mA
	Collector power dissipation		Pc	150	mW
Total power dissipation			P tot	170	mW
*2Isolation voltage		V iso	3 750	V <sub>rms</sub>	
Operating temperature			T opr	- 30 to + 100	°C
Storage temperature			T stg	- 40 to + 125	°C
*3 Soldering temperature			T sol	260	°C



## **■** Electro-optical Characteristics

 $(Ta = 25^{\circ}C)$ 

	Para	ameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
	Forward voltage		V <sub>F</sub>	$I_F = 20 \text{mA}$	-	1.2	1.4	V	
Input	Reverse current		$I_R$	$V_R = 4V$	-	-	10	μΑ	
	Terminal capacitance		Ct	V = 0, $f = 1kHz$	-	30	250	pF	
Output	Collector dark current PC356N PC358		PC356NT	I <sub>CEO</sub>	$V_{CE} = 20V, I_{F} = 0$		-	1 x 10 -7	A
			PC358		$V_{CE} = 40V, I_{F} = 0$	] -			
	Contestor cumiter		PC356NT	BV CEO	$I_C = 0.1 \text{mA}, I_F = 0$	80	-	-	V
			PC358			120	-	-	V
	Emitter-collector breakdown voltage		BV ECO	$I_E = 10 \mu\text{A}, I_F = 0$	6	-	-	V	
Transfer- charac- teristics	Current transfer ratio PC356NT PC358		CTD	$I_F = 1mA$ , $V_{CE} = 5V$	100	-	400	%	
			PC358	CTR	$I_F = 5mA$ , $V_{CE} = 5V$	50	-	600	%
	Collector-emitter saturation voltage		V <sub>CE(sat)</sub>	$I_F = 20mA$ , $I_C = 1mA$	-	-	0.2	V	
	Isolation resistance		R <sub>ISO</sub>	DC500V, 40 to 60% RH	5 x 10 <sup>10</sup>	1011	-	Ω	
	Floating capacitance			$C_{\rm f}$	V = 0, $f = 1MHz$	-	0.6	1.0	pF
	Response time	Rise time	PC356NT	t <sub>r</sub>		-	6	-	μs
			PC358		$V_{CE} = 2V$ , $I_{C} = 2mA$	-	4	18	μs
		Fall time	PC356NT		$R_L = 100\Omega$	-	8		μs
			PC358	$t_{\mathrm{f}}$		-	3	18	μs

<sup>\*1</sup> Pulse width $\leq$ =100 $\mu$ s, Duty ratio: 0.001

<sup>\*2 40</sup> to 60% RH, AC for 1 minute

<sup>\*3</sup> For 10 senconds

Fig. 1 Forward Current vs.

Ambient Temperature

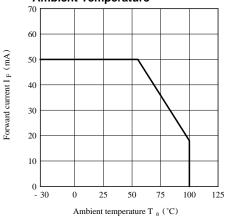


Fig. 3 Collector Power Dissipation vs.
Ambient Temperature

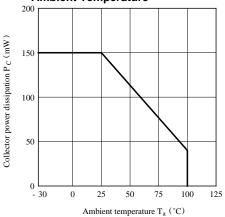


Fig. 5 Peak Forward Current vs. Duty Ratio

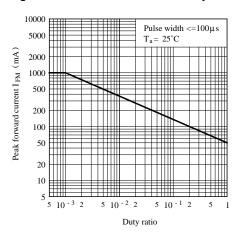


Fig. 2 Diode Power Dissipation vs.
Ambient Temperature

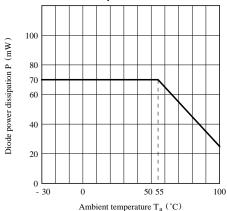


Fig. 4 Total Power Dissipation vs.
Ambient Temperature

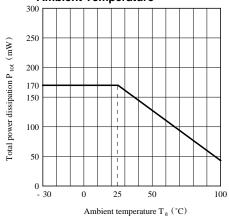


Fig. 6 Forward Current vs. Forward Voltage

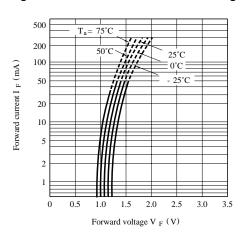


Fig. 7-a Current Transfer Ratio vs.
Forward Current (PC356NT)

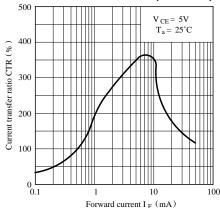


Fig. 8-a Collector Current vs.
Collector-emitter Voltage
(PC356NT)

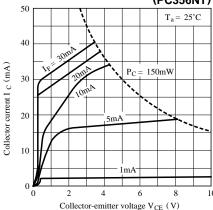


Fig. 9-a Relative Current Transfer Ratio vs.
Ambient Temperature

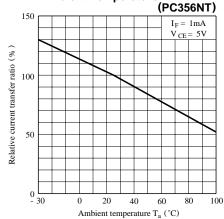


Fig. 7-b Current Transfer Ratio vs.

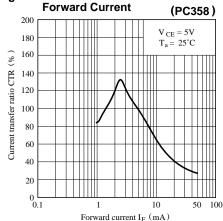


Fig. 8-b Collector Current vs.
Collector-emitter Voltage

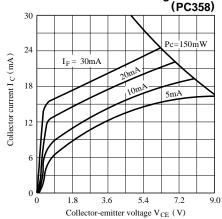


Fig. 9-b Relative Current Transfer Ratio vs.
Ambient Temperature

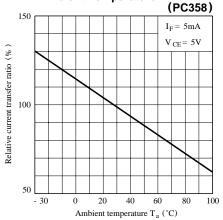


Fig.10-a Collector-emitter Saturation Voltage vs. Ambient Temperature

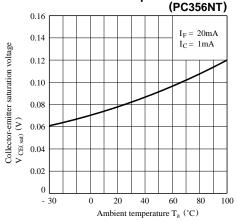


Fig.11-a Collector Dark Current vs.
Ambient Temperature

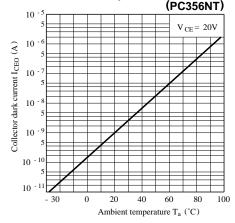


Fig.12-a Response Time vs. Load Resistance (PC356NT)

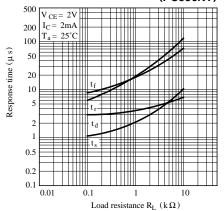


Fig.10-b Collector-emitter Saturation Voltage vs. Ambient Temperature

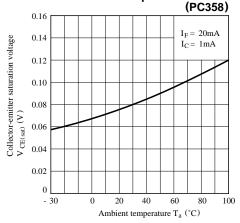


Fig.11-b Collector Dark Current vs.
Ambient Temperature

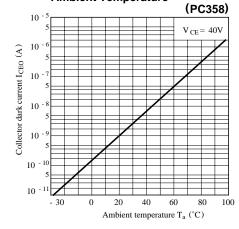
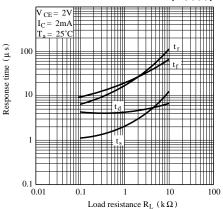


Fig.12-b Response Time vs. Load Resistance (PC358)



### **Test Circuit for Response Time**

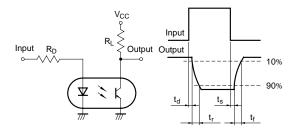


Fig.13-a Collector-emitter Saturation Voltage vs. Forward Current (PC356NT)

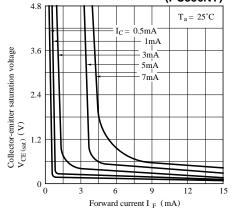
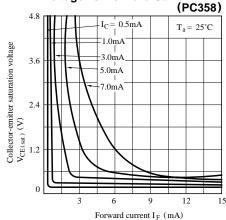
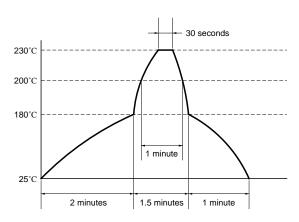


Fig.13-b Collector-emitter Saturation Voltage vs. Forward Current



## **■** Temperature Profile of Soldering Reflow



- One time soldering reflow is recommended within the condition of temperature and time profile shown below.
- (2) When using another soldering method such as infrared ray lamp, the temperature may rise partially in the mold of the device.

  Keep the temperature on the package of the device within the condition of above (1).
- Please refer to the chapter "Precautions for Use".

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